# Metal Whiskers



**Discussion for the UNOVIS Consortium** 



Jay Brusse / Perot Systems http://nepp.nasa.gov/whisker Dr. Henning Leidecker / NASA Goddard Lyudmyla Panashchenko / Univ. of MD-CALCE Graduate Student **UNOVIS Consortium Meeting** June 18, 2008

## Outline



- A Brief History of Metal Whiskers
- System Failure Modes Caused by Metal Whiskers
- Inspection Tips
- A Few Mitigation Strategies to Reduce Harm From Metal Whiskers



Zinc Whiskers on <u>Hot Dip Galvanized</u> Steel Pipe

*Cover Photo: Tin whiskers on Tin-Plated Beryllium Copper Card Guides on Space Shuttle* 

<u>NO WHISKER GROWTH THEORY TO BE DISCUSSED!!!</u>



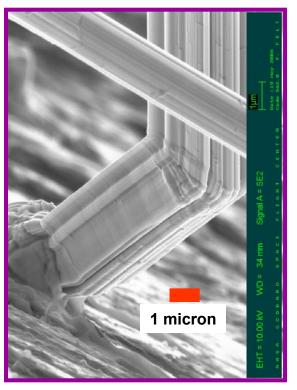
## What are Tin or Zinc or Cadmium Whiskers?

#### DESCRIPTION:

- Hair-like, metallic crystals that UNPREDICTABLY sometimes grow out from a metal surface
  - Straight or kinked filaments, nodules, odd-shaped eruptions
  - Filaments usually have uniform cross section along entire length
- Tin, Zinc and Cadmium coatings are most common sources
- Whiskers are also less frequently seen on metals like Indium, Gold, Silver, Lead, and other metals

#### • GROWTH TIMELINE:

- <u>Incubation</u>: Absence of growth may last from hours to years
- <u>Growth:</u> Accretion of metal ions at base of whisker NOT at tip
- <u>Rate of Growth</u>: < 1 mm/yr (typical) Highly variable (up to 9mm/yr reported)
- LENGTH: ~1mm or less (typical) Rarely up to 10 mm or more Log-normally distributed
- THICKNESS: A few microns (typical) Range 0.006 to >10 um 10 to >100 times thinner than a human hair!!!



*Tin Whiskers on Tin-Plated Electromagnetic Relay Terminals* 

# The Good News: Not All Tin, Zinc or Cadmium Surfaces Will Grow Whiskers (See Back Up Slide for Discussion)

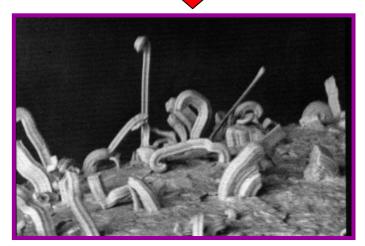
# The Bad News:

Current theories and test methods <u>DO NOT</u> Enable prediction of the time-dependence of Population Density, Length, Thickness

A useful theory should identify what we must control to make confident predictions. Such a theory has remained elusive



# "Whiskers" are NOT "Dendrites"



- Whisker Growth is
  - Filament-like, rarely branching
  - Outward/Away from surface
- Whisker Growth **Does NOT** Require
  - Solvents
  - Electric Fields
  - Moisture, Elevated temperature, T-Cycle



- Dendrite Growth is
  - Fern-like, branching
  - Along a surface
- Dendrite Growth <u>DOES</u> Require
  - Solvents to dissolve the metal into ionic species
  - Electric Fields to cause ion migration

## Metal Whiskers "The Early Years"



- 1946: Cadmium Whiskers

   H. Cobb (Aircraft Radio Corp.)
   publishes earliest "known" account of
   CADMIUM whiskers on cadmium coated variable air capacitor plates.
   Whiskers induced electrical shorting
   in military equipment. These events
   occurred during WW II (~1942 1943)
- 1952: Tin and Zinc Whiskers Since Cadmium coatings resulted in shorting, Tin and Zinc were used instead. But then K.G. Compton, A. Mendizza, and S.M. Arnold (Bell Labs) reported shorting caused by whiskers from these coatings too!



*Tin Whiskers on 1960's Era Variable Air Capacitor* 

## Whisker Resistant Metal Coatings "The Quest"



- 1950s and 60's <sup>[1] [2]</sup>: Bell Labs worked through the periodic table to determine whether addition of some element to a Tin coating would "inhibit" whiskering
  - Adding 0.5 1% (by weight) or more of <u>Lead (Pb)</u> into tin inhibits whiskering
  - Alloying with metals other than Pb sometimes ENHANCES whiskering
- Since 1990s:

To inhibit whiskers most US MIL specs require adding Pb to tin coatings used near electronics

- For design margin, the concentration is usually named as 2% to 3% Pb by weight
- However, international legislation that restricts use of Pb in consumer electronics is affecting availability of "Pb" bearing tin coatings

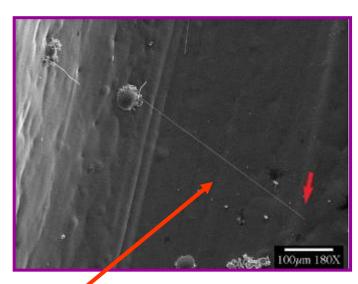
### • What additives quench Zn & Cd whiskers?

 We don't know, but certainly NOT chromate conversion finishes!



[2] P. Key, "Surface Morphology of Whisker Crystals of Tin, Zinc and Cadmium," IEEE Electronic Components Conference, pp. 155-160, May, 1970

June 18, 2008

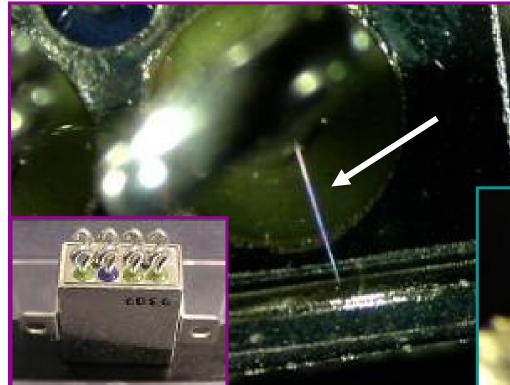




Zinc Whiskers Growing from Zinc-Plated <u>Yellow Chromate</u> Steel Bus Rail



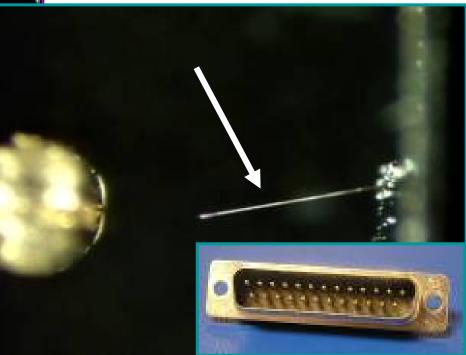
# **Examples of Metal Whiskers**



**Tin Plated Electromagnetic Relay Tin Whisker Shorting** Terminals and Case

**NOTE: Procurement Spec PROHIBITED Tin-Plating!** 

Tin-Plated D-Sub Connector Shell Advertised as "RoHS Compliant"



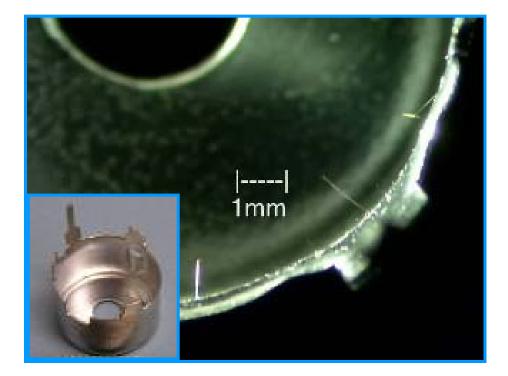
June 18, 2008



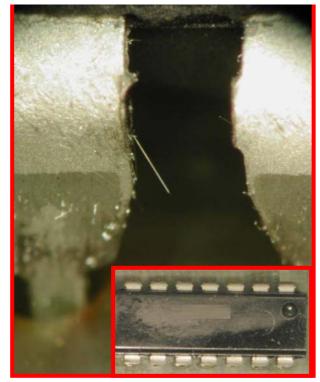
# **Examples of Metal Whiskers**

#### Tin-Plated Transformer Can Tin Whiskers "As Received"

Note: Supplier Changed to Pure Tin WITHOUT Warning Customers



Tin-Plated DIP IC Leads Tin Whiskers Produce Field Failure in Power Plant After 20 Years in Field!



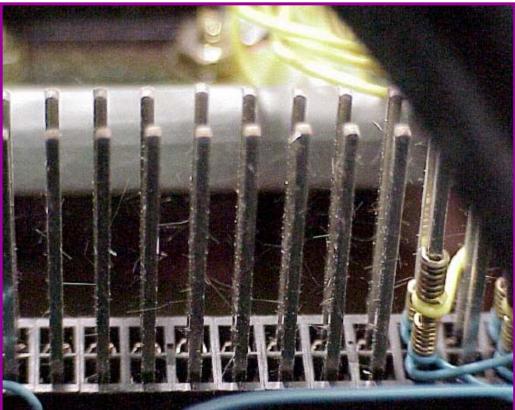
http://nepp.nasa.gov/whisker/anecdote/20year

June 18, 2008



# **Examples of Metal Whiskers**

Tin-Plated Wire Wrap Pins Tin Whiskers

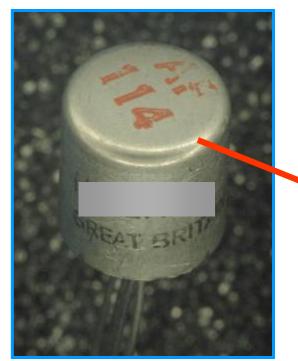


GE Power Management, "Technical Service Bulletin: Tin Whiskers in MOD10 Relays", March 27, 2000 http://www.geindustrial.com/pm/support/dls/dlssb01.pdf

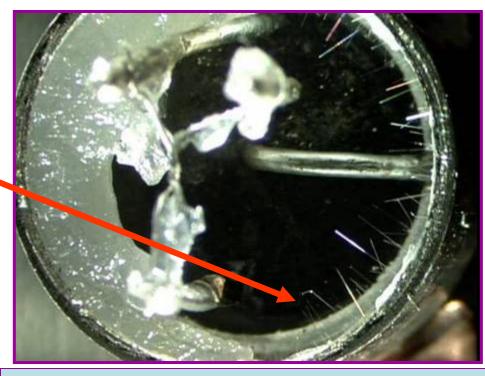
June 18, 2008



## **Guess What's Lurking Inside?**



1960's Vintage Transistor



Transistor Package is Tin-Plated Inside.

Many Radio Malfunctions Have Been Attributed to Whiskers Shorting Case to Terminals

http://www.vintage-radio.net/forum/showthread.php?t=5058

June 18, 2008

## 2006- NASA Goddard Presented A Partial History of Documented Metal Whisker Problems



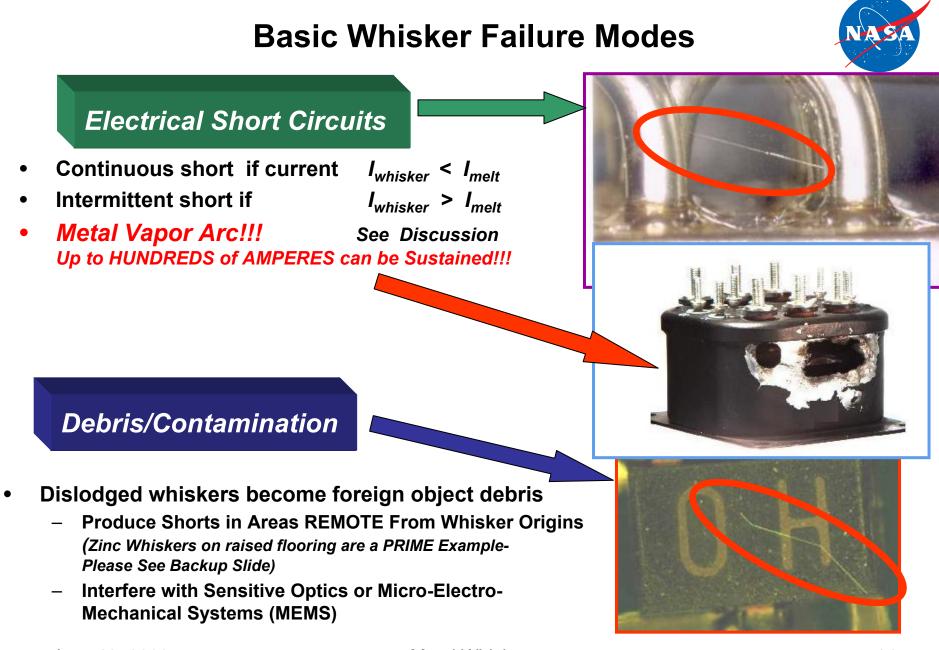
http://nepp.nasa.gov/whisker/reference/tech\_papers/2006-Leidecker-Tin-Whisker-Failures.pdf

	Industry	Whiskers on? Rotary Switch Failure Cause	Whiskers on?
Industry         1948       Telecom Equipme         1954       Telecom Equipme         1959       Telecom Equipme         1958       Computer Hardware         2001       Hi-Rel	Failure Cause       Zinc Whiskers       Industry	Rotary Switch	Whickers on?
1948       Telecom Equipme       Year**       Application       Industry         1954       Telecom Equipme       1990       Apnea Monitors       Medical (RECALL)         1959       Telecom Equipme       1990       Apnea Monitors       Medical (RECALL)         1959       Telecom Equipme       1990       Duane Arnold Nucles       Year**       Application         1959       Telecom Equipme       1992       Missile Program "C"       2000       GALAXY VII (Side 2)         1959       Telecom Equipme       1995       Telecom Equipme       1995       Telecom Equipme         1959       Telecom Equipme       1996       Computer Routers       2000       SOLIDARIDAD I (Side 2)         1959       Telecom Equipme       1998       Aerospace       2001       GALAXY IIIR (Side 1)         1959       Telecom Equipme       1998       Computer Hardware       2001       Hi-Rel	Failure Cause       Zinc Whiskers       Industry	Rotary Switch	Whickers on?
1954       Telecom Equipme       Industry       Industry         1959       Telecom Equipme       1990       Apnea Monitors       Medical (RECALL)         1959       Telecom Equipme       1990       Duane Arnold Nuclea Power Station       Year**       Application         1959       Telecom Equipme       1992       Missile Program "C"       2000       GALAXY VII (Side 2)         1959       Telecom Equipme       1995       Telecom Equipme       2000       Missile Program "D"         1959       Telecom Equipme       1996       Computer Routers       2000       SOLIDARIDAD I (Side 2)         1959       Telecom Equipme       1998       Aerospace       2001       GALAXY IIIR (Side 1)         1959       Telecom Equipme       1998       Computer Hardware       2001       Hi-Rel	Zinc Whiskers	Rotary Switch	Whickers on?
1959       Telecom Equipme       1990       Apnea Monitors       Medical (RECALL)         1990       Duane Arnold Nuclea       Year**       Application         1990       Missile Program "C"       2000       GALAXY VII (Side 2)         1959       Telecom Equipme       1995       Telecom Equipme       2000       Missile Program "D"         1959       Telecom Equipme       1995       Telecom Equipme       2000       Power Mgmt Modules         1959       Telecom Equipme       1996       Computer Routers       2000       SOLIDARIDAD I (Side 2)         1959       Telecom Equipme       1998       Aerospace       2001       GALAXY IIIR (Side 1)         1959       Telecom Equipme       1998       Computer Hardware       2001       Hi-Rel	Industry		Whiskers on 2
1930       Aprication       Infection         1990       Duane Arnold Nuclea       Year** Application         1990       Power Station       2000       GALAXY VII (Side 2)         1993       Govt. Electronics       2000       Missile Program "D"         1959       Telecom Equipme       1995       Telecom Equipme       2000       Missile Program "D"         1959       Telecom Equipme       1996       Computer Routers       2000       SOLIDARIDAD I (Side 2)         1959       Telecom Equipme       1996       MIL Aerospace       2001       GALAXY IIIR (Side 1)         1959       Telecom Equipme       1998       Computer Hardware       2001       Hi-Rel	Industry		Whickors on 2
Power Station     Image: Complexity of the state in the s		Failure Cause	Whickore on?
1992Missile Program "C" 19932000GALAXY VII (Side 2)19951993Govt. Electronics2000Missile Program "D"1959Telecom Equipmen1995Telecom Equipment2000Power Mgmt Modules1959Telecom Equipmen1996Computer Routers2000SOLIDARIDAD I (Side 2)1959Telecom Equipmen1998Aerospace2001GALAXY IIIR (Side 1)1959Telecom Equipmen1998Computer Hardware2001Hi-Rel	Space (Complete Loss)		WINSKEIS UN?
1932 Missile Program Co         1933 Govt. Electronics         1959 Telecom Equipme         1996 MIL Aerospace         1998 Aerospace Electronic         2001 GALAXY IIIR (Side 1)         1998 Computer Hardware         2001 Hi-Rel	Space (Complete Loss)		
1993Govt. Electronics2000Missile Program "D"1959Telecom Equipme1995Telecom Equipme2000Power Mgmt Modules1959Telecom Equipme1996Computer Routers2000SOLIDARIDAD I (Side 2)1959Telecom Equipme1998Aerospace2001GALAXY IIIR (Side 1)1958Computer Hardware2001Hi-Rel		Tin Whiskers	Relays
1959       Telecom Equipme       1995       Telecom Equipme       2000       Missile Program "D"         1959       Telecom Equipme       1996       Computer Routers       2000       SOLIDARIDAD I (Side 2)         1959       Telecom Equipme       1996       MIL Aerospace       2001       GALAXY IIIR (Side 1)         1959       Telecom Equipme       1998       Aerospace Electroni       2001       GALAXY IIIR (Side 1)         1998       Computer Hardware       2001       Hi-Rel       2001       Hi-Rel			
1959       Telecom Equipme       1996       Computer Routers       2000       SOLIDARIDAD I (Side 2)         1959       Telecom Equipme       1996       MIL Aerospace       2001       GALAXY IIIR (Side 1)         1959       Telecom Equipme       1998       Aerospace Electronii       2001       GALAXY IIIR (Side 1)         1998       Computer Hardware       2001       Hi-Rel       2001       Director		Tin Whiskers	Terminals
1996         MIL Aerospace         2001         Collocation (Inclusion)         Collocation (Inclusion) <thcollocation (inclusion)<="" th="">         Collocation (Inclusion</thcollocation>		Tin Whiskers	Connectors
1998 Computer Hardware 2001 Hi-Rel	Space (Complete Loss)	Tin Whiskers	Relays
1998 Computer Hardware 2001 Hi-Rel	Space	Tin Whiskers	Relays
		Tin Whiskers	Ceramic Chip Caps
	Power	Tin Whiskers	Relays
1998 Dresden nuclear Pov 2001 Space Ground Test Eqpt	Ground Support	Zinc Whiskers	Bus Rail
Station	Space	Tin Whiskers	Relays
2002 Electric Power Plant	Power	Tin Whiskers	Microcircuit Leads
1986 F15 Radar 1998 GALAXY IV (Side 2) 2002 GPS Receiver		Tin Whiskers	RF Enclosure
1986 Heart Pacemaker 2002 MIL Aerospace		Tin Whiskers	Mounting Hardware (nuts)
1986 Phoenix Missile 1998 GALAXY VII (Side 1) 2002 Military Aircraft		Tin Whiskers	Relays
1987 Dresden nuclear 1998 Military Aerospace 2002 Nuclear Power Plant	Power	Tin Whiskers	Potentiometer
Station 1998 PAS-4 (Side 1) 2003 Commercial Electronics		Tin Whiskers	RF Enclosure
1999 Eng Computer Center 2003 Missile Program "E"	Military	Tin Whiskers	Connectors
1999 SOLIDABIDAD L (Side 2003 Missile Program "F"		Tin Whiskers	Relays
1960 Missile Program		Tin Whiskers	Ckt Breaker
	Military	Tin Whiskers	Waveguide
2005 Communications	Radio (1960s vintage)	Tin Whiskers	Transitor TO Package
199X Telecom Equipment 2005 Millstone Nuclear Power	Power	Tin Whiskers	Diode (Axial Leads)

# These are ~10% of the Problems We Know About

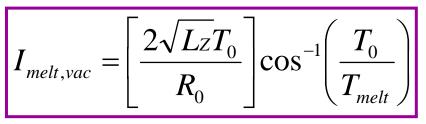


# "There is a name for those who suppose that doing the same thing will produce different results. That name is 'Idiot'." - Albert Einstein





## Metal Whisker Melting Current -- Pt. 1



See Backup Slides for Derivation

- Where  $Lz \sim 2.45^{*}10^{-8} (V/K)^2$  is the Lorenz number,  $T_{melt} = melting$  temperature,  $T_0 = ambient$  temperature,  $R_0 = whisker$  resistance at ambient

Material	T <sub>melt</sub>	l <sub>melt, vac</sub>	$V_{melt} = R_0 * I_{melt, vac}$
Tin	505.1K	87.5 mV / R <sub>0</sub>	88 mV
Cadmium	594.2K	97.1 mV / R <sub>0</sub>	97 mV
Zinc	692.7K	104.4 mV / R <sub>0</sub>	104 mV

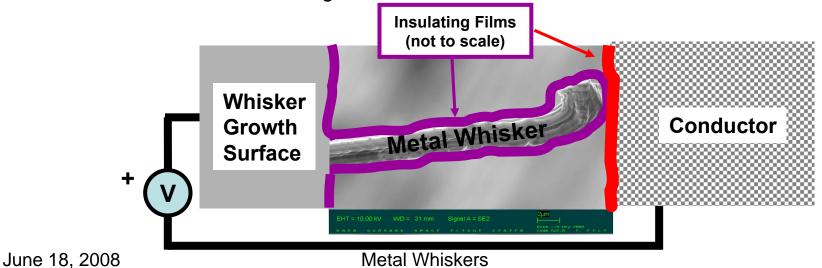
If V <sub>whisker</sub> > V <sub>melt</sub>	
Then the Whisker will Fuse Open	

But there is MORE to this story



## Metal Whisker Melting Current -- Pt. 2

- Electrically insulating films naturally form on metal surfaces INCLUDING surfaces of metal whiskers
  - Examples: oxides, hydroxides, sulfides, moisture films, etc.
- Direct MECHANICAL contact by the whisker to another conductor does NOT guarantee ELECTRICAL contact
  - For Electrical Contact, the potential difference must exceed "dielectric breakdown" of the insulating films
  - For tin and zinc whiskers, independent groups have confirmed the film breakdown can range from ~ 0.2V to ~ 45V



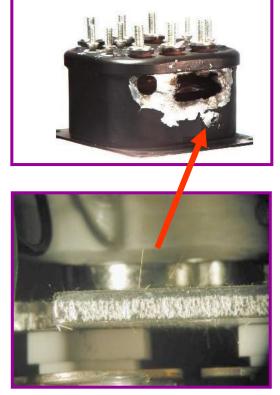
## Sustained Metal Vapor Arcing Initiated by Metal Whisker

- When a metal whisker shorts two conductors at different potentials, a sustained arc can occur if
  - Current is high enough to <u>vaporize</u> the whisker (i.e., metal gas)
  - Voltage is high enough to ionize the metal gas
- Sustained arcing between metal conductors is possible for voltages as low as ~12 to 14 volts when
  - Arc gap is <u>SMALL</u> ~ a few tens of microns
  - Available current > ~100 to 300 mA
  - See "Electrical Contacts Part III" by Paul G. Slade
- However, as arc gap increases, sustaining the arc requires
  - Higher voltage to ionize the metal gas
  - Higher current to boil enough additional metal gas to keep plasma dense enough to sustain it
  - Vacuum (i.e., low pressure) is NOT required, but can reduce the threshold voltage and current required for arcing
- Relevant metal vapor arc testing by NASA of FM08 style fuses with metal filaments ~5 mm long
  - ~75 volts at more than 30 amperes is needed to generate a sustained arc across this arc gap when P ~1 torr

June 18, 2008

Metal Whiskers





*Tin Whiskers Growing on Armature Of Relay Produced Metal Vapor Arc* 

G. Davy, "<u>Relay Failure Caused by Tin</u> <u>Whiskers</u>", Northrop Grumman, Technical Article, October 2002 http://nepp.nasa.gov/whisker/reference/tech\_ papers/davy2002-relay-failure-caused-by-tinwhiskers.pdf

# How do YOU Relieve the "Stress" from Whiskers?



Option A Man with Facial Whiskers Does Yoga



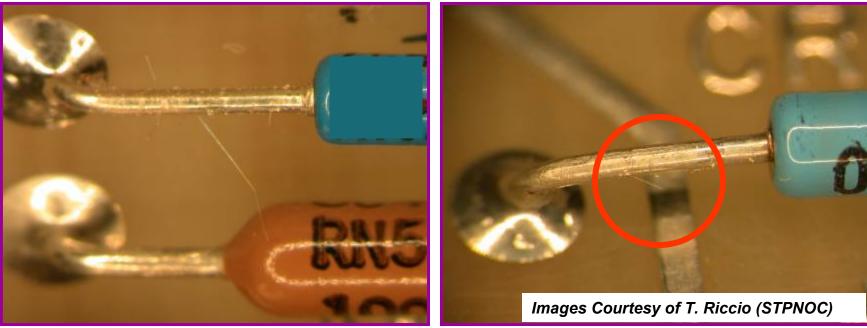
Option B Men with Metal Whiskers Use "Innovative" Techniques



## A Case for Whisker Mitigation Strategies?



Tin Whiskers on Tin-Plated Axial Leaded Diodes



- Diode Leads were <u>NOT Hot Solder Dipped</u> prior to assembly; thus leaving large surface area of pure tin coating prone to whisker growth
- PWB and components were <u>NOT Conformal Coated</u>; thus leaving adjacent conductors exposed to bridging by whisker growth

June 18, 2008

## Another Case for Whisker Mitigation Strategies?



#### Metal Whiskers on External Case of Potentiometers



- No electrically insulating materials were used on the metal cases
- Metal whiskers bridging between the cases or from case to adjacent components can cause circuit malfunction

## **Three Whisker Mitigation Strategies**



Mitigation – to make <u>less</u> severe or painful Merriam-Webster Dictionary

## Risk "Mitigation" ≠ Risk "Elimination"

- Avoid Use of Whisker Prone Surface Finishes
  - "Trust, But VERIFY" Certificates of Conformance!
  - Perform independent materials composition analysis using X-ray Fluorescence (XRF), Energy Dispersive X-ray Spectroscopy (EDS), etc.
- Conformal Coat Electrically Insulating Barriers
  - Benefit #1: When applied on top of a whisker prone surface, conformal coat can sometimes keep whiskers from pushing through
  - Benefit #2: When applied to a distant conductor, can block whiskers from electrically shunting distant conductors
  - Benefit #3: Provides insulating barrier against loose conductive debris
- Remove/Replace Tin Finishes When Practical
  - Hot Solder Dip using lead-tin (Pb-Sn) solders
  - "First, Do No Harm" Principle

June 18, 2008

## NASA Goddard Whisker Mitigation Study Conformal Coat (Uralane 5750\* Polyurethane) ~9 Years of Office Ambient Storage



#### • Specimens:

- 1" x 4"x 1/16" Brass 260
- Tin-Plated 200 microinches
- A few intentional scratches created after plating to induce localized whisker growth

### • Conformal Coating:

- Uralane 5750 on ½ of sample
- Nominal Thickness = 2 mils
- Locally THIN Regions also examined

## • Storage Conditions:

Office Ambient ~ 9 years

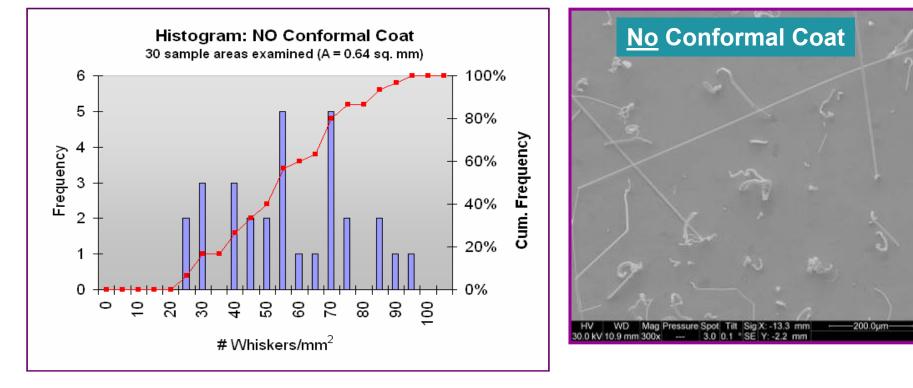


\* Uralane™ 5750 now known as Arathane™ 5750

## NASA Goddard Whisker Mitigation Study Control Areas – <u>No</u> Conformal Coat 9-Years of Office Ambient Storage



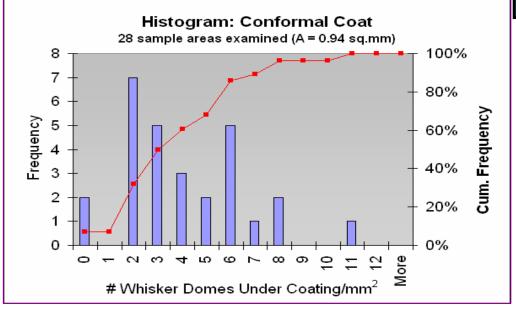
- Control Areas Grew Whiskers Abundantly within the First Year. After 9 years of storage we found the following:
  - 30 areas each 0.64 mm<sup>2</sup> were randomly examined for whisker density
  - Avg: 55 ± 19.6 whiskers / mm<sup>2</sup>
  - Range: 23 to 95 whiskers / mm<sup>2</sup>



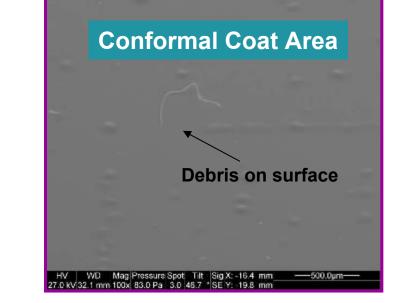
## NASA Goddard Whisker Mitigation Study Uralane 5750 – 2 Mils Thick 9-Years of Office Ambient Storage



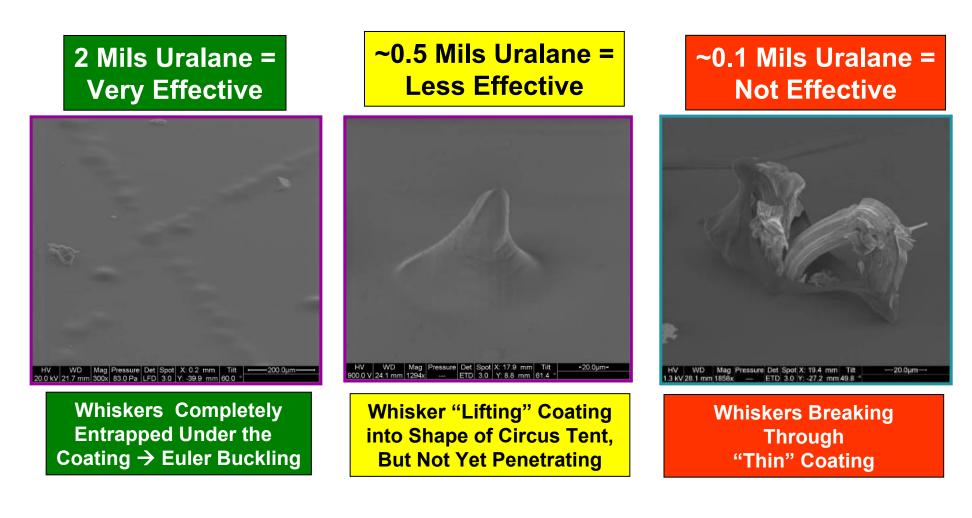
- Conformal Coated Areas Grew Whiskers Too within the First Year. After 9 years of storage we find the following:
  - To date ALL whiskers are contained beneath the coating that is <u>2 mils thick</u>
  - SEM cannot see INTO coating. Thus we see only "domes" caused by whiskers that lift coating slightly
  - Avg:  $3.4 \pm 2.6$  domes / mm<sup>2</sup>
  - Range: 0 to 10.6 domes / mm<sup>2</sup>



We suspect we are only counting "thick" whiskers in this statistic because the "thin" ones mechanically buckle before they can lift the coating enough to produce visible "domes"



## NASA Goddard Whisker Mitigation Study Uralane 5750 Conformal Coat -9-Years of Office Ambient Storage



## **Euler Buckling Axial Force Required to Buckle a Metal Whisker**

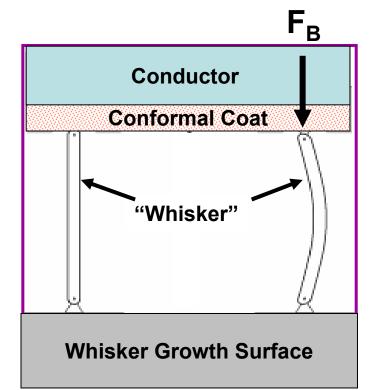


$$F_B = \frac{\pi^2 EI}{(KL)^2} \approx \left(\frac{\pi^3 \cdot E}{32}\right) \left(\frac{d^4}{L^2}\right)$$

- E = Young's Modulus of whisker material,
- I = Area Moment of Inertia,

(e.g.  $I = \pi d^4 / 64$  for circular cross section)

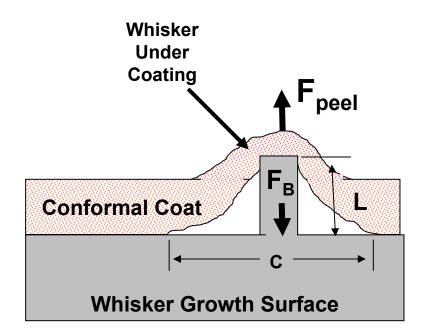
- L = Length of whisker,
- K = Column Effective Length Factor
  - K = 0.5 for whisker fixed at both ends
  - K = 0.7 for fixed at one end, pinned at other



## Whiskers Lift and Peel Conformal Coat Until Whisker Buckles <u>OR</u> Coating Fails

(F<sub>peel</sub> vs. F<sub>Buckle</sub>)

- As whisker first emerges it is short and stiff thus F<sub>B</sub> > F<sub>peel</sub> and whisker begins to lift the coating forming a "circus tent" with height L = length of whisker;
- "Tent" joins the surface at a circle of circumference C ~  $2\pi$ QL,
  - Q describes the details of tent-like shape
- To peel conformal coating up and away from the surface, one needs to apply a force (F<sub>peel</sub>) proportional to the circumference:
  - F<sub>peel</sub> = Φ \* C = 2 pi Q Φ L
     Φ = peel strength of material which describes the adhesion of the coating to the tin, and the effect of the separation angle. It also depends on the rate at which the coating is peeled away.



*Uralane* 5750 has better self-cohesion than adhesion to a tin surface

### **Additional Analysis Pending**

## Will Whiskers Buckle Before Puncturing the Coating on a Distant Surface?

• The displacement of the conformal coat due to a whisker pushing against the coating is:

$$D = \left(\frac{1-\nu^2}{E_{coat}}\right) \left(\frac{F_B}{d}\right) \approx \left(\frac{\pi^3}{32}\right) \left(1-\nu^2\right) \left(\frac{E_W}{E_{coat}}\right) \left(\frac{d^3}{L^2}\right)$$

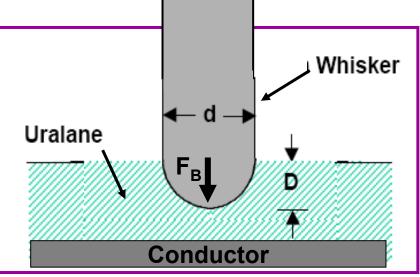
Where

- D = Displacement of conformal coat
- v = Poisson's ratio

 $E_{coat}$  = Young's Modulus of coating

 $E_W$  = Young's Modulus of Whisker

- d = "Diameter" of whisker
- L = Length of whisker
- F<sub>B</sub> = Euler Buckling Strength of the whisker





- Numerous sorts of coatings have been tried:
  - Reports of success vary from "none" to "perfect", sometimes for the same sort of coating.
- NASA GSFC has used Uralane 5750, applied to pre-primed tin-plated surfaces to a thickness of 2 mils (=50 micrometers) +/- 10%:
  - After ~9 years of office ambient storage, these surfaces have whiskered abundantly, but the number of whiskers escaping through the 2 mil thick areas has been zero
- Dr. Thomas Woodrow (Boeing) has studied Urethane (acrylic) coatings, a silicone coating, and Parylene C coating of varying thicknesses up to ~ 4 mils (= 100 micrometers):
  - Some whiskers have penetrated even the thickest coatings when exposed to 25°C / 97% R.H.
  - "Evaluation of Conformal Coatings as a Tin Whisker Mitigation Strategy, Part 2", T. Woodrow, SMTAI, Sept. 2006 <u>http://nepp.nasa.gov/whisker/reference/tech\_papers/2006-Woodrow-Conformal-Coating-PartII.pdf</u>

## Effects of Conformal Coating -- 2



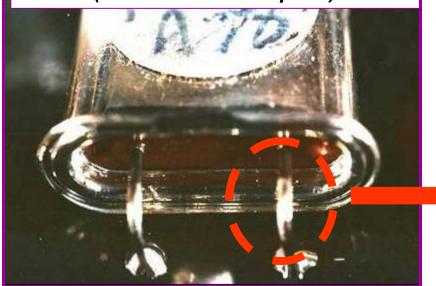
- Conclusion 1: 2 mils Uralane 5750 Provides Substantial Protection
  - Uralane 5750, applied to at least 2 mils thickness, is a substantial improvement over an uncoated surface.
- Conclusion 2: Understand YOUR Conformal Coating Processes
  - Conformal coating processes can leave "weak zones" with less than the nominal thickness of coating.
    - Areas shadowed during application
    - Coating flows/thins prior to cure
  - Thinner coatings are more prone to whisker puncture
- Conclusion 3: Even "Poor" Coatings Can Offer Some Protection
  - Long whiskers bend easily (Euler Buckling) and are less likely to penetrate even thin conformal coat.
  - Conformal coat protects against a conductive bridge from detached whiskers lying across a pair of coated conductors

## Hot Solder Dip Benefits & Limitations



Field Failure ONE Year After Assembly

Crystal with Tin-Plated Kovar Leads (with Nickel Underplate)



- Leads were <u>Hot Solder Dipped</u> (Sn63Pb37) <u>within 50 mils</u> of Glass Seal BEFORE Mounting to enhance solderability
- Dip was not 100% of leads due to concerns of inducing harm to glass seal

 Tin Whiskers (~60 mils) Grew on

 NON-Dipped
 Region Shorting to Case

 Causing Crystal to Malfunction

- No Whiskers on Hot Solder Dipped Surface
- ABUNDANT whiskers on the Non-Dipped Surface

June 18, 2008

## Optical Inspection for Metal Whiskers



- Basic Equipment:
  - Binocular Microscope
  - Light Source: Flex Lighting PREFERRED over Ring Lamp
- Freedom to tilt sample and/or lighting to illuminate whisker facets is VERY IMPORTANT





June 18, 2008

## Evidence of "Absence of Whiskers"? (Optical Microscopy)



#### **Tin-Plated Lock Washer**



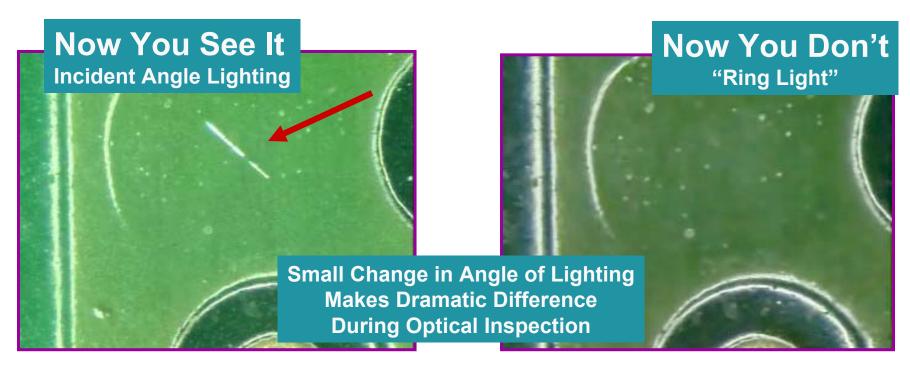
#### The absence of evidence is NOT evidence of absence

# Field Technicians and Failure Analysts Need To Be Acquainted with Metal Whiskers!!!



NASA GSFC has published videos to aid in optical inspection for metal whiskers

# http://nepp.nasa.gov/whisker/video



Video Demonstration Optical Inspection For Metal Whiskers (Click Image to Start Video)



Optical Inspection of Metal Whiskers

Now You See It Now You Don't!!!

Jay Brusse/Perot Systems at NASA Goddard **Contact Information** 



Jay Brusse Perot Systems at NASA Goddard Space Flight Center Jay.A.Brusse@nasa.gov

# Work Performed in Support of the NASA Electronic Parts and Packaging (NEPP) Program

Acknowledgment to Dr. Michael Osterman University of MD – Center for Advanced Life Cycle Engineering (CALCE)

NASA Tin and Other Metal Whisker WWW Site

http://nepp.nasa.gov/whisker

June 18, 2008



# **Backup Slides**

### Why Are Tin, Zinc, Cadmium Still Used?



- Not all Tin (or Zinc or Cadmium) surfaces grow whiskers!
  - Rough estimate: 3% to 30% do whisker.
- Not all metal whiskers cause shorts
  - Application matters: geometry, electrical potentials, circuit sensitivity to shorting
  - Rough estimate: 3% to 30% do short.
- Not all whisker-induced shorts are traced to whiskers
  - They are very hard to see and failure analysis techniques often destroy evidence
  - Rough estimate: 0% to 10% are correctly traced.
- Not all identified whisker adventures are reported
  - Rough estimate: 0% to 3% are reported, once identified
- Hence, we expect between 0.00% and 0.03% of shorting problems caused by these coatings to be reported
  - While some 0.1% to 10% of these coatings are actually causing shorts.
  - With such a few public cases, many say "What, me worry?"
- Whiskering is dramatically inhibited when 0.5% (or more) lead (Pb) is added to Tin coatings: the shorting rate then approaches zero
  - This has been the case for the Hi-Rel community
  - But Pb use is being restricted by international legislation, and so the shorting rate may jump to 10% from zero => SWATCH GROUP <==</li>

### "The Five Stages of Metal Whisker Grief"

By Henning Leidecker



Adapted from Elisabeth Kubler-Ross in her book "On Death and Dying", Macmillan Publishing Company, 1969

#### Denial

"Metal whiskers?!? We ain't got no stinkin' whiskers! I don't even think metal whiskers exist! I KNOW we don't have any!"

#### Anger

"You say we got whiskers, I rip your \$%#@ lungs out! Who put them there --- I'll murderize him! I'll tear him into pieces so small, they'll fit under one of those \*^&\$#% whiskers!"

#### Bargaining

"We have metal whiskers? But they are so small. And you have only seen a few of them. How could a few small things possibly be a problem to our power supplies and equipment? These few whiskers should be easy to clean up."

#### Depression

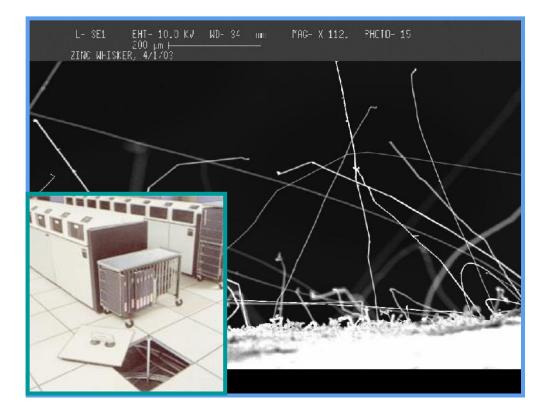
"Dang. Doomed. Close the shop --- we are out of business. Of all the miserable bit joints in all the world, metal whiskers had to come into mine... I'm retiring from here... Going to open a 'Squat & Gobble' on the Keys. "

#### Acceptance

"Metal whiskers. How about that? Who knew? Well, clean what you can. Put in the particle filters, and schedule periodic checks of what the debris collectors find. Ensure that all the warrantees and service plans are up to date. On with life."



## **Examples of Metal Whiskers**



Zinc-Coated Computer Room Floor Tiles Zinc Whiskers Cadmium-Plated Connector Shell Cadmium Whiskers



### A Few Recent Whisker Experiences: It's Not Just Tin Whiskers!!!



### • Tin Whiskers:

- 2005: Tin Whiskers on *diode leads* shut down *Millstone Nuclear Power Plant*
- 2006: Tin whiskers on <u>card rails</u> discovered in <u>Space Shuttle Transportation System</u> Some 100 to 300 million whiskers were in OV-105's boxes
- 2006: Tin whiskers on <u>watch crystals</u> reported by <u>SWATCH Group</u>. 30% of new RoHScompliant Sn-Cu solder sprouting whiskers. 5% catastrophically shorted within months.

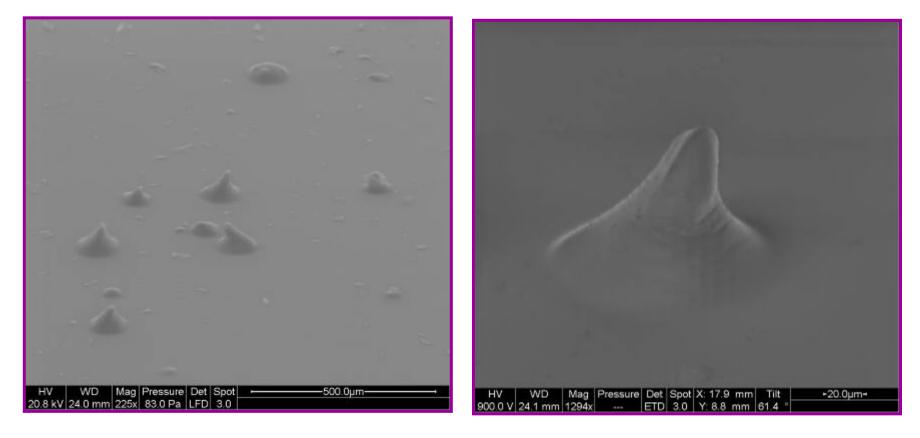
### • Zinc Whiskers:

- 2005: Zinc whiskers on <u>raised floor tiles</u> cripple <u>Colorado State Government</u> data center. Forced to build a new "disaster recovery center"
- 2005: Zinc whiskers on <u>raised floor tiles</u> destroy 75% of the computer equipment in a particular data center. <u>Investigation takes ~8 months to properly identify root cause</u>
- 2006: Zinc whiskers identified as root cause of persistent <u>NAVY weapon system</u> <u>failures</u>
- Cadmium Whiskers:
  - 2006: Cadmium whiskers found on *electrical switch* proposed for spaceflight program
  - 2007: Cadmium whiskers on *connector shells* cause failure during T-Vac testing

Tin Whiskers Forming "Circus Tents" in Thin Uralane 5750 Conformal Coat -9-Years of Office Ambient Storage

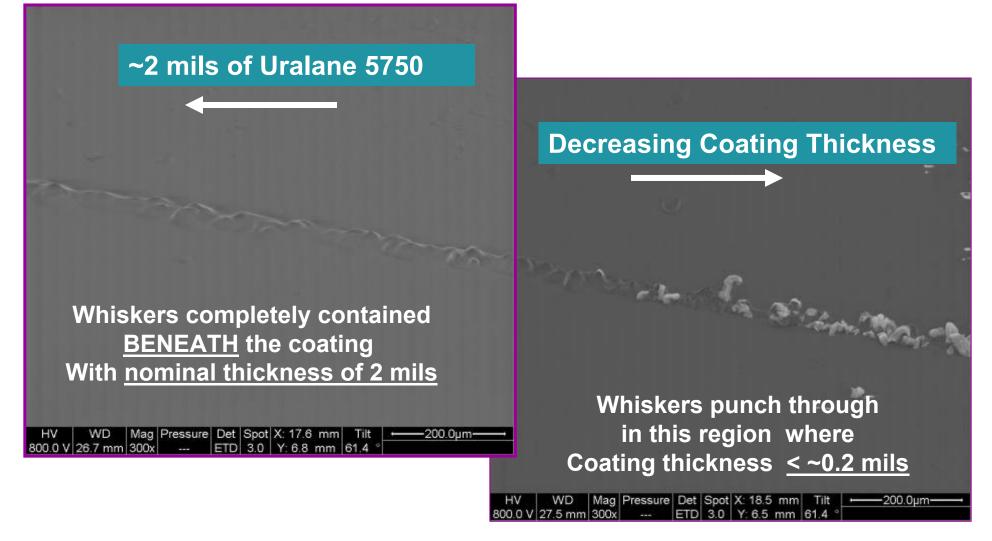


**Coating Thickness < 0.5 Mil** 



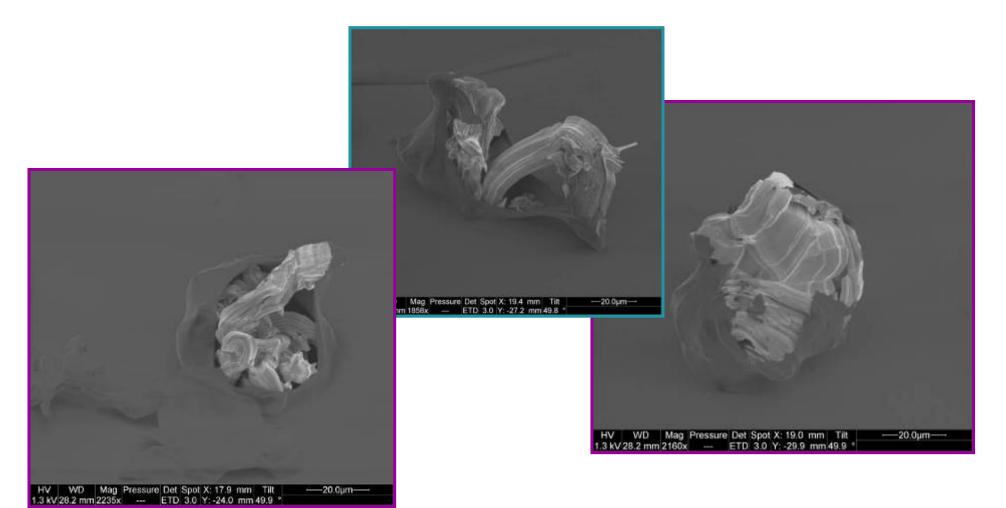
### NASA Goddard Whisker Mitigation Study Whisker Puncture vs. Coating Thickness





*Tin Whiskers Rupturing THIN Coating* ~0.1 to 0.2 *Mils* Uralane 5750 Conformal Coat 9-Years of Office Ambient Storage





June 18, 2008

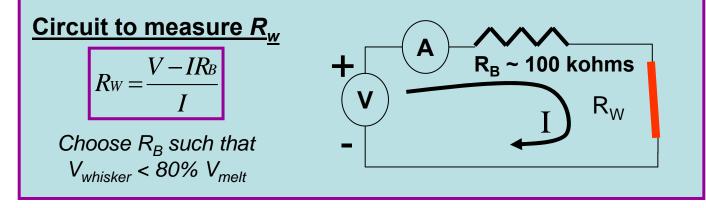


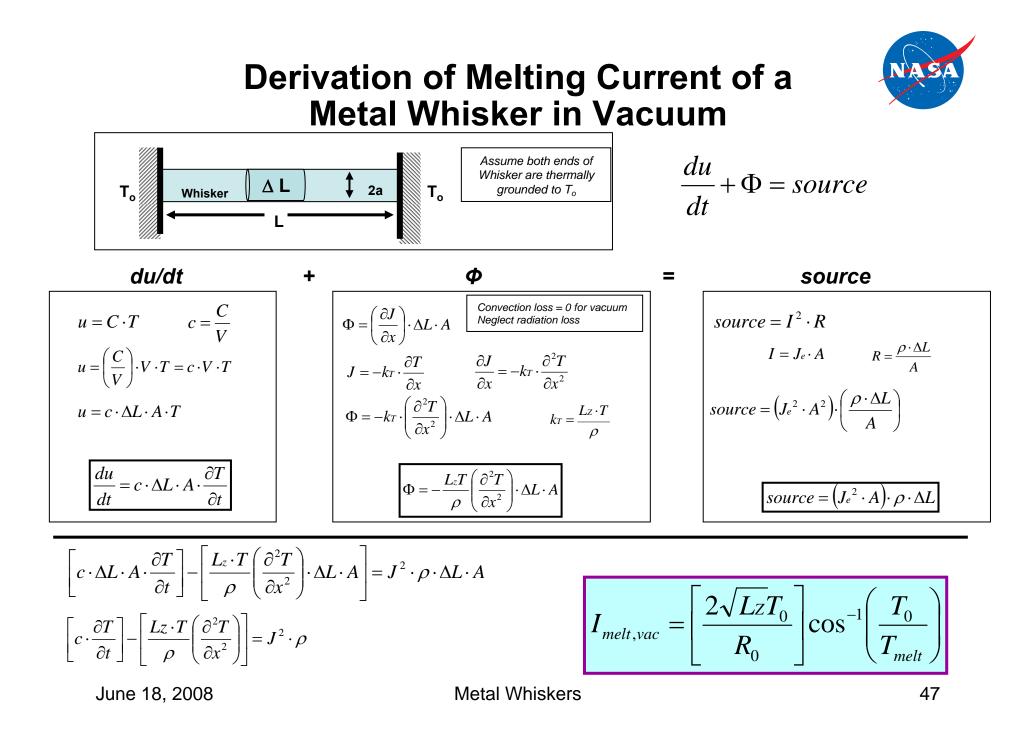
### Thank Goodness for Euler Buckling and Conformal Coat on this PWB!!!



Photo Credit: M&P Failure Analysis Laboratory The Boeing Company Logistics Depot Circuit to Measure Resistance of a Metal Whisker

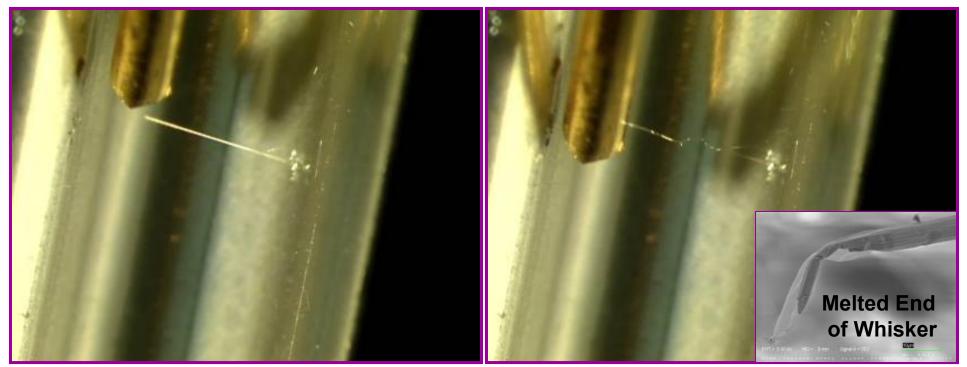
- Use of a simple "Ohmmeter" to measure the resistance of a metal whisker is NOT preferred
  - Ohmmeter may supply V<sub>out</sub> < V<sub>breakdown</sub> for the insulating films (oxides, moisture) that form on a metal whisker
  - Ohmmeter may supply V<sub>out</sub> > V<sub>melt</sub> causing the whisker to melt before resistance can be measured
- Instead, a variable power supply and a ballast resistor should be used to overcome the above complications
  - Adjust V<sub>out</sub> > V<sub>breakdown</sub> of insulating films on whisker
  - When  $V_{out} > V_{breakdown}$ ,  $R_B$  quickly drops  $V_{whisker} < V_{melt}$





### An Example of "Melting" a Tin Whisker





### **Before Contact**

1. Gold-Plated Test Probe has +3 Volts Relative to Tin Whisker

### **After Contact**

- 1. Tip of whisker micro-welds to gold test probe
- 2. Whisker melts mid-length
- 3. Small section of whisker root remains attached to substrate